



**ENGINEERED  
CONDUCTIVE  
MATERIALS**

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## SURFACE MOUNT

Product Designation	Description	Typical Application/Benefit	Application Method	Electrical Resistance Ohms - cm
<b>Silver Epoxy Adhesives</b>				
DB-1501	Silver epoxy, 1 component	SMD attachments, high shear strength, long stencil life	Stencil Print	0.0004 ohm-cm
DB-1509	Silver epoxy, 2 component	SMD attachments, high shear strength, long stencil life	Stencil Print	0.0004 ohm-cm
DB-1561	Silver epoxy, 2 component	SMD attachment, low temp cure	Needle Dispense	0.003 ohm-cm
<b>Under-fill Staking Compounds</b>				
UF-9526	Non-conductive under fill adhesive	SMD attachments, long dispense life	Needle Dispense	> 1,000 Mega Ohm
<b>Encapsulant</b>				
EC-9519	Non-conductive UV cure encapsulant	SMD top coat for protection	Needle Dispense	> 1,000 Mega Ohm